



Material Content Data Sheet



Halogen-Free

Sales Product Name	SLB 9665TT2.0 FW5.63	Issued	13. May 2021
MA#	MA002285184		
Package	PG-TSSOP-28-2	Weight*	108.67 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.586	5.14	5.14	51404	51404
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		105	
	non noble metal	zinc	7440-66-6	0.046	0.04		420	
	non noble metal	iron	7439-89-6	0.913	0.84		8402	
	non noble metal	copper	7440-50-8	37.070	34.11	35.00	341136	350063
wire	noble metal	gold	7440-57-5	0.274	0.25	0.25	2519	2519
encapsulation	organic material	carbon black	1333-86-4	0.304	0.28		2796	
	plastics	epoxy resin	-	9.420	8.67		86686	
	inorganic material	silicondioxide	60676-86-0	51.049	46.98	55.93	469780	559262
leadfinish	non noble metal	tin	7440-31-5	1.539	1.42	1.42	14167	14167
plating	noble metal	silver	7440-22-4	0.775	0.71	0.71	7136	7136
glue	plastics	epoxy resin	-	0.420	0.39		3862	
	noble metal	silver	7440-22-4	1.259	1.16	1.55	11587	15449
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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